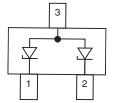


Features

- Two-line ESD protection device
- ESD immunity acc. IEC 61000-4-2
 - ± 30 kV contact discharge
 - ± 30 kV air discharge
- ESD capability according to AEC-Q101: human body model: class H3B: > 8 kV
- Space saving SOT-23 package
- AEC-Q101 qualified available



ABSOLUTE MAXIMUM RATINGS GSOT03C

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 μs; single shot	1	30	А
Peak pulse current	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t_p = 8/20 μ s; single shot	Іррм	30	Α
Dook pulse pouce	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 μs; single shot		369	W
Peak pulse power	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, $t_p = 8/20 \mu s$; single shot	P _{PP}	504	W
CCD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	V	± 30	kV
ESD immunity	Air discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
Operating temperature	Junction temperature	ΤJ	-55 to +150	°C
Storage temperature		T _{STG}	-55 to +150	°C



ABSOLUTE MAXIMUM RATINGS GSOT04C

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	1	30	А
Peak pulse current	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	ІРРМ	30	А
Dook pulse power	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	D	429	W
Peak pulse power	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	P _{PP}	564	W
CCD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	V	± 30	kV
ESD immunity	Air discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
Operating temperature	Junction temperature	ΤJ	-55 to +150	°C
Storage temperature		T _{STG}	-55 to +150	°C

ABSOLUTE MAXIMUM RATINGS GSOT05C

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	I	30	А
Peak pulse current	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot		30	Α
Dock pulse power	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot		480	W
Peak pulse power	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	P _{PP}	612	W
ESD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	V	± 30	kV
E3D IIIIIIIIIIIII	Air discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
Operating temperature	Junction temperature	Τ _J	-55 to +150	°C
Storage temperature		T _{STG}	-55 to +150	°C

ABSOLUTE MAXIMUM RATINGS GSOT08C

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
Peak pulse current	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, $t_p = 8/20 \mu s$; single shot	1	18	А
reak puise current	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t_p = 8/20 μ s; single shot	І _{РРМ}	18	А
Peak pulse power	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, $t_p = 8/20 \mu s$; single shot	P _{PP}	345	W
reak puise power	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	ГРР	400	W
ESD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	V	± 30	kV
E3D IIIIIIdility	Air discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
Operating temperature	Junction temperature	Τ _J	-55 to +150	ů
Storage temperature		T _{STG}	-55 to +150	°C



ABSOLUTE MAXIMUM RATINGS GSOT12C

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	1	12	Α
Peak pulse current	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	ІРРМ	12	А
Pook pulso power	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	D	312	W
Peak pulse power	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	P _{PP}	337	W
CCD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	V	± 30	kV
ESD immunity	Air discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
Operating temperature	Junction temperature	ΤJ	-55 to +150	°C
Storage temperature		T _{STG}	-55 to +150	°C

ABSOLUTE MAXIMUM RATINGS GSOT15C

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	1	8	А
Peak pulse current	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	ІРРМ	8	А
Dook pulse power	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	D	345	W
Peak pulse power	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	P _{PP}	400	W
CCD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	1/	± 30	kV
ESD immunity	Air discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
Operating temperature	Junction temperature	Τ _J	-55 to +150	°C
Storage temperature		T _{STG}	-55 to +150	°C



ABSOLUTE MAXIMUM RATINGS GSOT24C

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 μs; single shot	1	5	А
Peak pulse current	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t_p = 8/20 μ s; single shot	ІРРМ	5	А
Dook pulse power	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 μs; single shot		235	W
Peak pulse power	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, $t_p = 8/20 \mu s$; single shot	P _{PP}	240	W
CCD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses	1/	± 30	kV
ESD immunity	Air discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
Operating temperature	Junction temperature	ΤJ	-55 to +150	°C
Storage temperature		T _{STG}	-55 to +150	°C

ABSOLUTE MAXIMUM RATINGS GSOT36C

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE	UNIT
	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	I	3.5	А
Peak pulse current	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	ІРРМ	3.5	А
Dook pulse power	Pin 1 to 3 or pin 2 to 3 acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	2	248	W
Peak pulse power	Pin 1 to 2 or pin 2 to 1; pin 3 not connected acc. IEC 61000-4-5, t _p = 8/20 µs; single shot	P _{PP}	252	W
ESD immunity	Contact discharge acc. IEC 61000-4-2; 10 pulses		± 30	kV
ESD immunity	Air discharge acc. IEC 61000-4-2; 10 pulses	V _{ESD}	± 30	kV
Operating temperature	Junction temperature	ΤJ	-55 to +150	°C
Storage temperature		T _{STG}	-55 to +150	°C



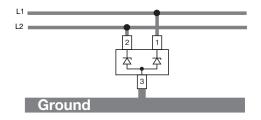
BIAs-MODE (2-line Bidirectional Asymmetrical protection mode)

With the GSOTxxC two signal- or data-lines (L1, L2) can be protected against voltage transients. With pin 3 connected to ground and pin 1 and pin 2 connected to a signal- or data-line which has to be protected. As long as the voltage level on the data- or signal-line is between 0 V (ground level) and the specified Maximum Reverse Working Voltage (V_{RWM}) the protection diode between pin 2 and pin 3 and between pin 1 and pin 3 offers a high isolation to the ground line. The protection device behaves like an open switch.

As soon as any positive transient voltage signal exceeds the breakdown voltage level of the protection diode, the diode becomes conductive and shorts the transient current to ground. Now the protection device behaves like a closed switch. The Clamping Voltage (V_C) is defined by the breakdown voltage (V_{BR}) level plus the voltage drop at the series impedance (resistance and inductance) of the protection diode.

Any negative transient signal will be clamped accordingly. The negative transient current is flowing in the forward direction through the protection diode. The low Forward Voltage (V_F) clamps the negative transient close to the ground level.

Due to the different clamping levels in forward and reverse direction the GSOTxxC clamping behavior is Bidirectional and Asymmetrical (BiAs).

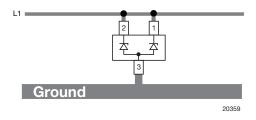




If a higher surge current or peak pulse current (I_{PP}) is needed, both protection diodes in the GSOTxxC can also be used in parallel in order to "double" the performance.

This offers:

- double surge power = double peak pulse current (2 x I_{PPM})
- half of the line inductance = reduced clamping voltage
- half of the line resistance = reduced clamping voltage
- double line capacitance (2 x C_D)
- double reverse leakage current (2 x I_R)



ELECTRICAL CHARACTERISTICS GSOT03C

(T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 3 or pin 2 to pin 3

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			2	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			3.3	V
Reverse voltage	at I _R = 100 μA	V _R	3.3			V
Reverse current	at V _R = 3.3 V	I _R			10	0µA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	4.0	4.6	5.5	V
Poverse elemping voltage	at I _{PP} = 1 A	Vc		5.7	7.5	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 30 \text{ A}$	v _C		10	12.3	V
Forward clamping voltage	at I _{PP} = 1 A	V _F		1	1.2	V
Forward clamping voltage	at $I_{PP} = I_{PPM} = 30 \text{ A}$	٧F		4.5		V
Capacitance	at V _R = 0 V; f = 1 MHz			420	600	pF
Сараспапсе	at V _R = 1.6 V; f = 1 MHz	- C _D		260		pF



ELECTRICAL CHARACTERISTICS GSOT04C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 3 or pin 2 to pin 3

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			2	lines
Reverse stand-off voltage	Max. reverse working voltage	V _{RWM}			4	V
Reverse voltage	at I _R = 20 μA	V_R	4			V
Reverse current	at V _R = 4 V	I _R			20	μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	5	6.1	7	V
Poverse elemning veltage	at I _{PP} = 1 A	V		7.5	9	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 30 A$	V _C		11.2	14.3	V
Forward alamping valtage	at I _{PP} = 1 A	V _F		1	1.2	V
Forward clamping voltage	at $I_{PP} = I_{PPM} = 30 \text{ A}$	VF		4.5		V
Capacitance	at V _R = 0 V; f = 1 MHz	C		310	450	pF
Сараспансе	at V _R = 2 V; f = 1 MHz	- C _D		200		pF

ELECTRICAL CHARACTERISTICS GSOT05C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 3 or pin 2 to pin 3

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			2	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			5	V
Reverse voltage	at I _R = 10 μA	V_R	5			V
Reverse current	at V _R = 5 V	I _R			10	μΑ
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	6	6.8	8	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		7	8.7	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 30 \text{ A}$	vc		12	16	V
Forward clamping voltage	at I _{PP} = 1 A	V _F		1	1.2	V
Forward clamping voltage	at $I_{PP} = I_{PPM} = 30 \text{ A}$	VF		4.5		V
Oppositions	at V _R = 0 V; f = 1 MHz			260	350	pF
Capacitance	at $V_R = 2.5 \text{ V}$; f = 1 MHz	- C _D		150		pF

ELECTRICAL CHARACTERISTICS GSOT08C $(T_{amb} = 25 \text{ °C unless otherwise specified})$

between pin 1 to pin 3 or pin 2 to pin 3

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N channel			2	lines
Reverse stand-off voltage	Max. reverse working voltage	V _{RWM}			8	V
Reverse voltage	at I _R = 5 μA	V_R	8			V
Reverse current	at V _R = 8 V	I _R			5	μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	9	10	11	V
Deverse elemning veltage	at I _{PP} = 1 A	V		10.7	13	V
Reverse clamping voltage	at I _{PP} = I _{PPM} = 18 A	Vc		15.2	19.2	V
Converd elemning veltage	at I _{PP} = 1 A	V		1	1.2	V
Forward clamping voltage	at I _{PP} = I _{PPM} = 18 A	V_{F}		3		V
Consoitones	at V _R = 0 V; f = 1 MHz			160	250	pF
Capacitance	at V _R = 4 V; f = 1 MHz	- C _D		80		pF



ELECTRICAL CHARACTERISTICS GSOT12C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 3 or pin 2 to pin 3

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			2	lines
Reverse stand-off voltage	Max. reverse working voltage	V _{RWM}			12	V
Reverse voltage	at I _R = 1 μA	V_R	12			V
Reverse current	at V _R = 12 V	I _R			1	μΑ
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	13.5	15	16.5	V
Reverse clamping voltage	at I _{PP} = 1 A			15.4	18.7	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 12 A$	V _C		21.2	26	V
Forward clamping voltage	at I _{PP} = 1 A	V _E		1	1.2	V
Forward clamping voltage	at $I_{PP} = I_{PPM} = 12 A$	V _F		2.2		V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	C-		115	150	pF
Сараспансе	at $V_R = 6 V$; $f = 1 MHz$	- C _D		50		pF

ELECTRICAL CHARACTERISTICS GSOT15C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 3 or pin 2 to pin 3

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			2	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			15	V
Reverse voltage	at I _R = 1 µA	V_R	15			V
Reverse current	at V _R = 15 V	I _R		1		μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	16.5	18	20	V
Payaraa alamping valtage	at I _{PP} = 1 A	V		19.4	23.5	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 8 A$	V _C		24.8	28.8	V
Forward clamping voltage	at I _{PP} = 1 A	V _E		1	1.2	V
Forward clamping voltage	at I _{PP} = I _{PPM} = 8 A	VF		1.8		V
Capacitance	at V _R = 0 V; f = 1 MHz			90	120	pF
Сараспапсе	at V _R = 7.5 V; f = 1 MHz		C _D	35		pF

ELECTRICAL CHARACTERISTICS GSOT24C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 3 or pin 2 to pin 3

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			2	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			24	V
Reverse voltage	at I _R = 1 μA	V _R	24			V
Reverse current	at V _R = 24 V	I _R			1	μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	27	30	33	V
Deverse elemning valtage	at I _{PP} = 1 A	.,		34	41	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 5 A$	V _C		41	47	V
Forward alamaina valtaga	at I _{PP} = 1 A	V		1	1.2	V
Forward clamping voltage	at I _{PP} = I _{PPM} = 5 A	V _F		1.4		V
Canacitanas	at V _R = 0 V; f = 1 MHz	_		65	80	pF
Capacitance	at V _R = 12 V; f = 1 MHz	- C _D		20		pF



ELECTRICAL CHARACTERISTICS GSOT36C (T_{amb} = 25 °C unless otherwise specified)

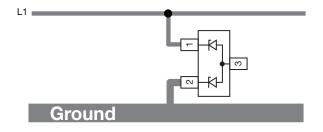
between pin 1 to pin 3 or pin 2 to pin 3

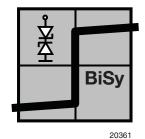
PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			2	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			36	V
Reverse voltage	at I _R = 1 µA	V_R	36			V
Reverse current	at V _R = 36 V	I _R			1	μΑ
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	39	43	47	V
Reverse clamping voltage	at I _{PP} = 1 A			49	60	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 3.5 A$	V _C		59	71	V
Forward clamping voltage	at I _{PP} = 1 A	\/_		1	1.2	V
Forward clamping voltage	at $I_{PP} = I_{PPM} = 3.5 A$	V _F		1.3		V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	C-		52	65	pF
Capacitarice	at $V_R = 18 \text{ V}$; $f = 1 \text{ MHz}$	C _D	12		pF	

BiSy-MODE (1-line bidirectional symmetrical protection mode)

If a bipolar symmetrical protection device is needed the GSOTxxC can also be used as a single line protection device. Therefore pin 1 has to be connected to the signal- or data-line (L1) and pin 2 to ground (or vice versa). Pin 3 must not be connected. Positive and negative voltage transients will be clamped in the same way. The clamping current through the GSOTxxC passes one diode in forward direction and the other one in reverse direction. The clamping voltage (V_C) is defined by the breakthrough voltage (V_{BR}) level of one diode plus the forward voltage of the other diode plus the voltage drop at the series impedances (resistances and inductances) of the protection device.

Due to the same clamping levels in positive and negative direction the GSOTxxC voltage clamping behaviour is bidirectional and symmetrical (BiSy).





ELECTRICAL CHARACTERISTICS GSOT03C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 2 or pin 2 to pin1; pin 3 not connected

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			1	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			3.8	V
Reverse voltage	at I _R = 100 μA	V_R	3.8			V
Reverse current	at V _R = 3.8 V	I _R			100	μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	4.5	5.3	6.2	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		7	8.4	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 30 \text{ A}$	vc		14	16.8	V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	C-		210	300	pF
Capacitarice	at $V_R = 1.6 \text{ V}$; $f = 1 \text{ MHz}$	- C _D		190		pF



ELECTRICAL CHARACTERISTICS GSOT04C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 2 or pin 2 to pin1; pin 3 not connected

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			1	lines
Reverse stand-off voltage	Max. reverse working voltage	V _{RWM}			4.5	V
Reverse voltage	at I _R = 20 μA	V_R	4.5			V
Reverse current	at V _R = 4.5 V	I _R			20	μΑ
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	5.5	6.8	7.7	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		7.5	9	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 30 \text{ A}$	v _C		15.7	18.8	V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	C-		155	225	pF
Сараспапсе	at $V_R = 2 V$; $f = 1 MHz$	- C _D		135		pF

ELECTRICAL CHARACTERISTICS GSOT05C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 2 or pin 2 to pin1; pin 3 not connected

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			1	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			5.5	V
Reverse voltage	at I _R = 10 μA	V_R	5.5			V
Reverse current	at $V_R = 5.5 \text{ V}$	I _R			10	μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	6.5	7.5	8.7	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		8.1	9.7	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 30 \text{ A}$	٧C		17	20.4	V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	- C _D		130	175	pF
Capacitance	at $V_R = 4 V$; $f = 1 MHz$	CD		100		pF

ELECTRICAL CHARACTERISTICS GSOT08C (T_{amb} = 25 °C unless otherwise specified) between pin 1 to pin 2 or pin 2 to pin1; pin 3 not connected

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			1	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			8.5	V
Reverse voltage	at I _R = 5 μA	V_R	8.5			V
Reverse current	at V _R = 8.5 V	I_R			5	μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	9.5	10.7	11.7	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		11.7	14	V
Reverse damping voltage	at $I_{PP} = I_{PPM} = 18 A$	۸G		18.5	22.2	V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	C-		80	125	pF
Сараспансе	at $V_R = 4 V$; $f = 1 MHz$	C _D		60		pF

ELECTRICAL CHARACTERISTICS GSOT12C (T_{amb} = 25 °C unless otherwise specified) between pin 1 to pin 2 or pin 2 to pin1; pin 3 not connected

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N channel			1	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			12.5	V
Reverse voltage	at I _R = 1 μA	V_R	12.5			V
Reverse current	at V _R = 12.5 V	I _R			1	μΑ
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	13.5	15.7	16.5	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		16.4	19.7	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 12 A$	٧C		23.4	28.1	V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	C-		58	75	pF
Сарасканс е	at $V_R = 7.5 \text{ V}$; $f = 1 \text{ MHz}$	C _D		36		pF



ELECTRICAL CHARACTERISTICS GSOT15C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 2 or pin 2 to pin1; pin 3 not connected

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			1	lines
Reverse stand-off voltage	Max. reverse working voltage	V _{RWM}			15.5	V
Reverse voltage	at I _R = 1 µA	V _R	15.5			V
Reverse current	at V _R = 15.5 V	I _R			1	μΑ
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	17	18.7	20.7	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		20.4	24.5	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 8 A$	VC VC		26.6	30.6	V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	- C _D		45	60	pF
Capacitarice	at $V_R = 7.5 \text{ V}$; f = 1 MHz			25		pF

ELECTRICAL CHARACTERISTICS GSOT24C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 2 or pin 2 to pin1; pin 3 not connected

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			1	lines
Reverse stand-off voltage	Max. reverse working voltage	V_{RWM}			24.5	V
Reverse voltage	at I _R = 1 μA	V_R	24.5			V
Reverse current	at V _R = 24.5 V	I _R			1	μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	27.5	30.7	33.7	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		34	41	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 5 A$	v.C		40	48	V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	C _D		33	40	pF
Capacitarice	at V _R = 12 V; f = 1 MHz			18		pF

ELECTRICAL CHARACTERISTICS GSOT36C (T_{amb} = 25 °C unless otherwise specified)

between pin 1 to pin 2 or pin 2 to pin1; pin 3 not connected

PARAMETER	TEST CONDITIONS/REMARKS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Protection paths	Number of li nes which can be protected	N _{channel}			1	lines
Reverse stand-off voltage	Max. reverse working voltage	V _{RWM}			36.5	V
Reverse voltage	at I _R = 1 µA	Vk	36.5			V
Reverse current	at V _R = 36.5 V	I _R			1	μA
Reverse breakdown voltage	at I _R = 1 mA	V_{BR}	39.5	43.7	47.7	V
Reverse clamping voltage	at I _{PP} = 1 A	V _C		50	60	V
Reverse clamping voltage	at $I_{PP} = I_{PPM} = 3.5 \text{ A}$	v _C		60	72	V
Capacitance	at $V_R = 0 V$; $f = 1 MHz$	- C _D		26	33	pF
Capacitarice	at $V_R = 18 \text{ V}$; f = 1 MHz			10		pF

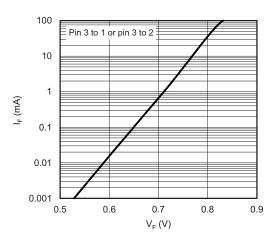


Fig. 1 - Typical Forward Current I_F vs. Forward Voltage V_F

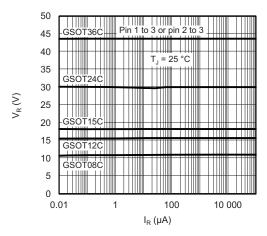


Fig. 2 - Typical Reverse Voltage V_R vs. Reverse Current I_R

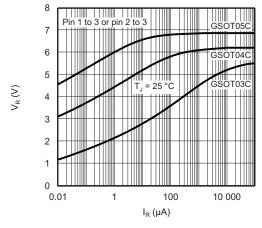


Fig. 3 - Typical Reverse Voltage V_R vs. Reverse Current I_R

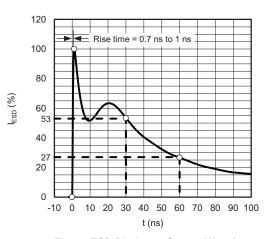


Fig. 4 - ESD Discharge Current Waveform According to IEC 61000-4-2 (330 $\,\Omega\,/$ 150 pF)

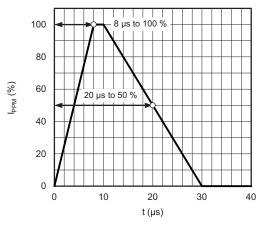


Fig. 5 - 8/20 µs Peak Pulse Current Waveform According to IEC 61000-4-5

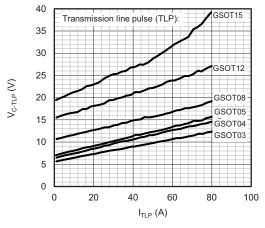


Fig. 6 - Typical Clamping Voltage vs. Peak Pulse Current

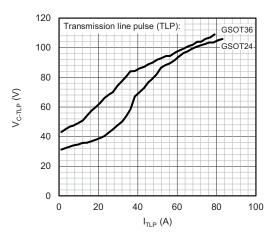


Fig. 7 - Typical Clamping Voltage vs. Peak Pulse Current

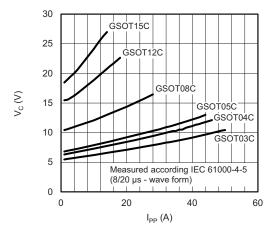


Fig. 8 - Typical Peak Clamping Voltage vs. Peak Pulse Current

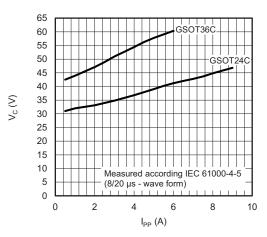


Fig. 9 - Typical Peak Clamping Voltage vs. Peak Pulse Current

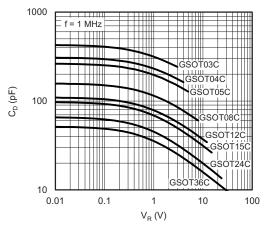
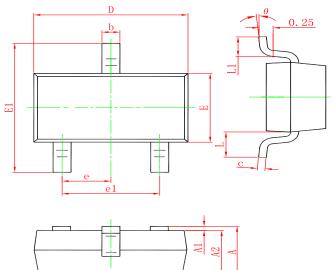


Fig. 10 - Typical Capacitance vs. Reverse Voltage

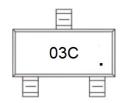


SOT-23 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
А	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode	Marking
UMW GSOT03C-E3-08	SOT-23	3000	Tape and reel	03C
UMW GSOT04C-E3-08	SOT-23	3000	Tape and reel	04C
UMW GSOT05C-E3-08	SOT-23	3000	Tape and reel	05C
UMW GSOT08C-E3-08	SOT-23	3000	Tape and reel	08C
UMW GSOT12C-E3-08	SOT-23	3000	Tape and reel	12C
UMW GSOT15C-E3-08	SOT-23	3000	Tape and reel	15C
UMW GSOT24C-E3-08	SOT-23	3000	Tape and reel	24C
UMW GSOT36C-E3-08	SOT-23	3000	Tape and reel	36C

单击下面可查看定价,库存,交付和生命周期等信息

>>UMW(友台半导体)